

PHOTOCOUPLER

PS2581AL1,PS2581AL2

LONG CREEPAGE HIGH ISOLATION VOLTAGE 4-PIN PHOTOCOUPLER

-NEPOC Series-

DESCRIPTION

★ The PS2581AL1, PS2581AL2 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor in a plastic DIP (Dual In-line Package) to realize an excellent cost performance.

Creepage distance and clearance of leads are over 8 millimeters.

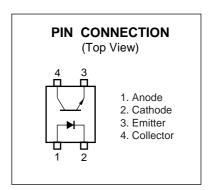
The PS2581AL2 is lead bending type (Gull-wing) for surface mounting.

FEATURES

- ★ Lead-free product : Solder plating specification Sn-Bi
 - · Long creepage and clearance distance (8 mm)
 - High isolation voltage (BV = 5 000 Vr.m.s.)
 - High-speed switching ($t_r = 5 \mu s$ TYP., $t_f = 7 \mu s$ TYP.)
 - UL, BSI, CSA, NEMKO, DEMKO, SEMKO, FIMKO approved
- ★ DIN EN60747-5-2 (VDE0884 Part2) approved

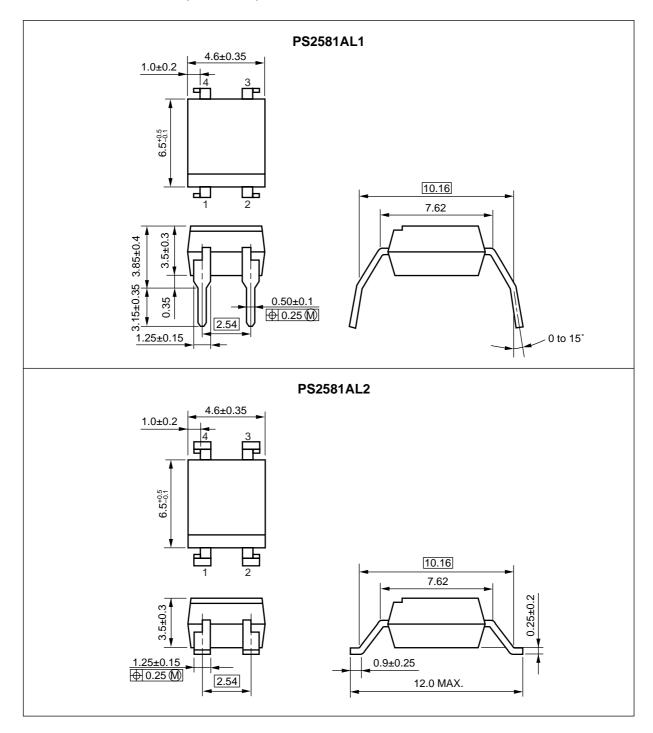
APPLICATIONS

- Power supply
- Telephone/FAX.
- FA/OA equipment
- · Programmable logic controller



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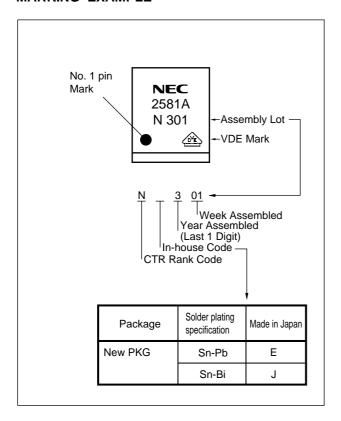
PACKAGE DIMENSIONS (UNIT: mm)



PHOTOCOUPLER CONSTRUCTION

Parameter	Unit (MIN.)		
Air Distance	8 mm		
Outer Creepage Distance	8 mm		
Inner Creepage Distance	4 mm		
Isolation Thickness	0.4 mm		

★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Package	Packing Style	Safety Standard Approval	Solder plating Specification	Application Part Number ^{⁴1}
PS2581AL1	4-pin DIP	Magazine case 100 pcs	Standard products	Sn-Pb	PS2581AL1
PS2581AL2			(UL, CSA, BSI, NEMKO,		PS2581AL2
PS2581AL2-E3		Embossed Tape 1 000 pcs/reel	SEMKO, DEMKO, FIMKO,		
PS2581AL2-E4			DIN EN60747-5-2		
PS2581AL1-A		Magazine case 100 pcs	(VDE0884 Part2)	Sn-Bi	PS2581AL1
PS2581AL2-A			Approved products)		PS2581AL2
PS2581AL2-E3-A		Embossed Tape 1 000 pcs/reel			
PS2581AL2-E4-A					

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage		6	V
	Forward Current (DC)	lF	30	mA
	Power Dissipation Derating	⊿P _D /°C	1.5	mW/°C
	Power Dissipation	Po	150	mW
	Peak Forward Current ^{⁴1}	I FP	0.5	Α
Transistor	Collector to Emitter Voltage	VCEO	70	V
Emitter to Collector Voltage Collector Current		VECO	5	V
		lc	30	mA
	Power Dissipation Delay	⊿Pc/°C	1.5	mW/°C
	Power Dissipation	Pc	150	mW
Isolation Voltage ^{'2}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100	°C
Storage Temperature		T _{stg}	-55 to +150	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} AC voltage for 1 minute at $T_A = 25^{\circ}C$, RH = 60% between input and output

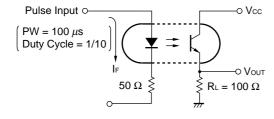
ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lr	V _R = 5 V			5	μΑ
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		10		pF
Transistor	Collector to Emitter Dark Current	ICEO	VcE = 70 V, IF = 0 mA			100	nA
Coupled	Current Transfer Ratio	CTR	IF = 5 mA, VcE = 5 V	50		300	%
	Collector Saturation Voltage	VCE (sat)	I _F = 10 mA, I _C = 2 mA		0.13	0.3	V
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.4		pF
	Rise Time ^{*2}	tr	Vcc = 10 V, Ic = 2 mA, R _L = 100 Ω		5		μs
	Fall Time*2	tf			7		

*1 CTR rank

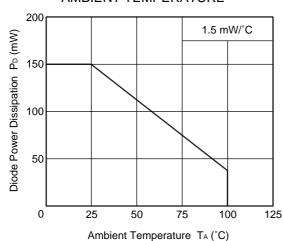
N : 50 to 300 (%) H : 80 to 160 (%) Q : 100 to 200 (%) W : 130 to 260 (%)

*2 Test circuit for switching time

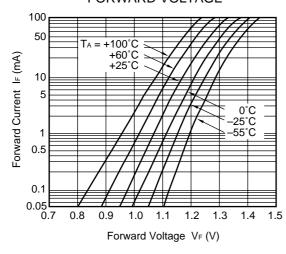


TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

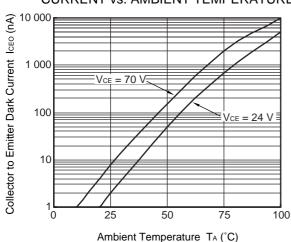
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



FORWARD CURRENT vs. FORWARD VOLTAGE

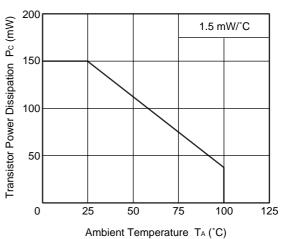


COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

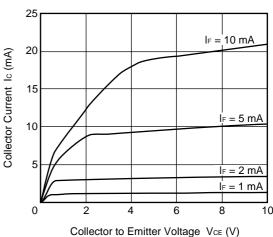


Remark The graphs indicate nominal characteristics.

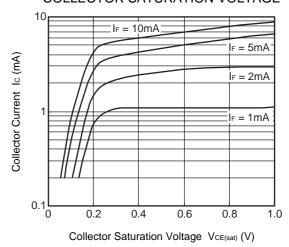
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



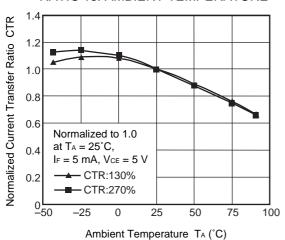
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



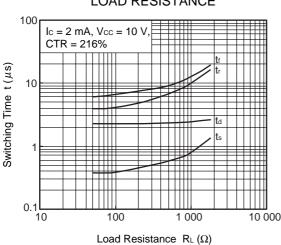
COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE



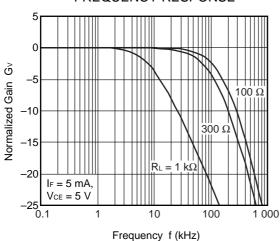
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE

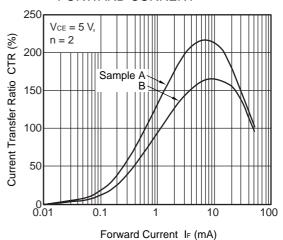


FREQUENCY RESPONSE



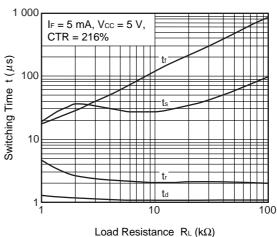
Remark The graphs indicate nominal characteristics.

CURRENT TRANSFER RATIO vs. FORWARD CURRENT

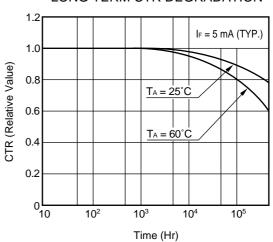


Tornara Garrone ii (iii)

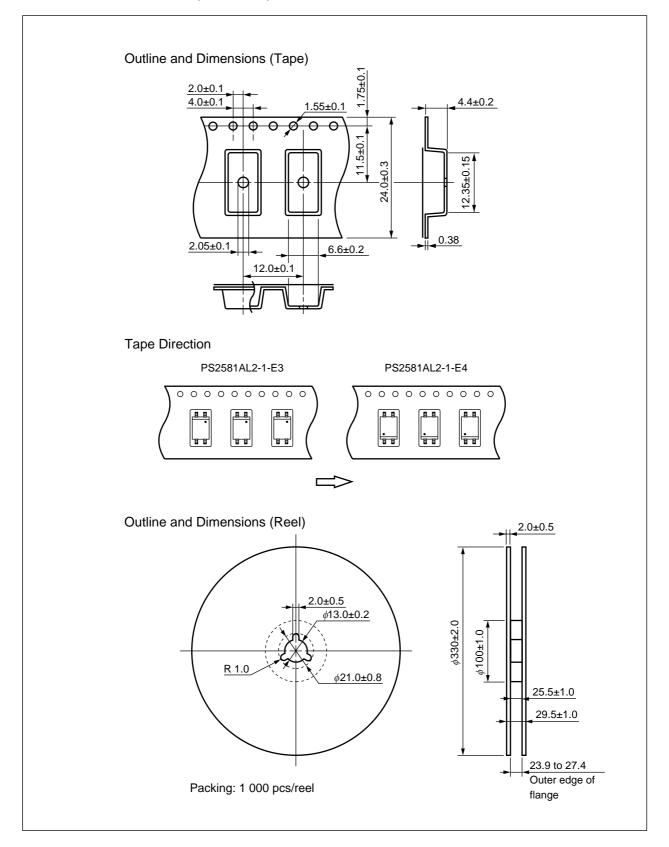
SWITCHING TIME vs. LOAD RESISTANCE



LONG TERM CTR DEGRADATION



TAPING SPECIFICATIONS (UNIT: mm)



NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

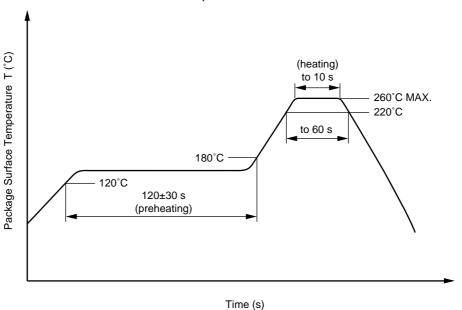
Time of peak reflow temperature
 Time of temperature higher than 220°C
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times
 One (Allowed to be dipped in solder including plastic mold portion.)

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

★ (3) Soldering by soldering iron

Peak temperature (lead part temperature) 350°C or below
 Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

★ 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- **2.** Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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